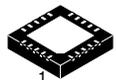


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

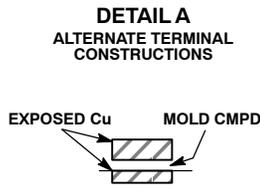
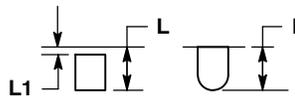
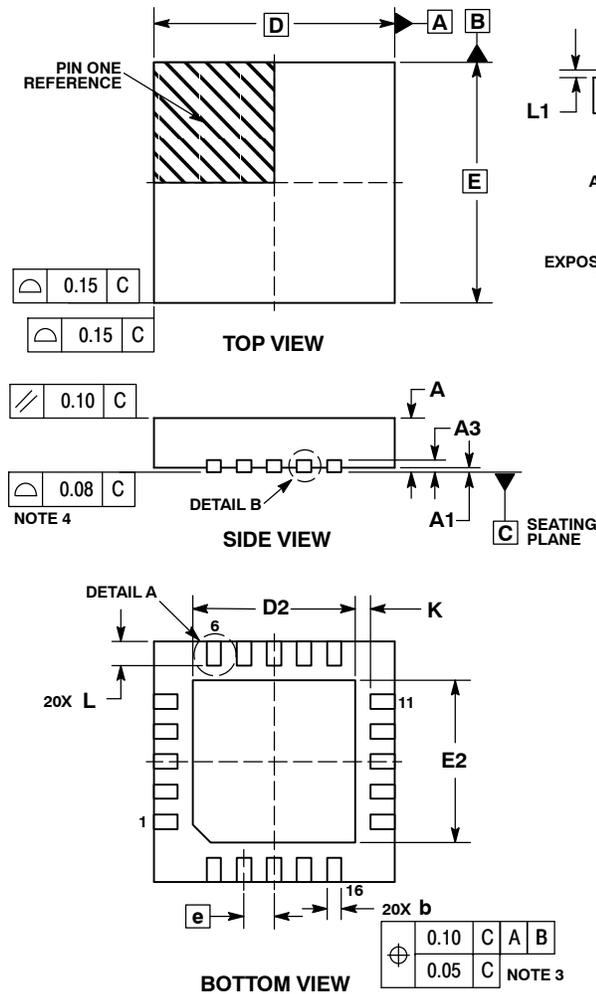
ON Semiconductor®



SCALE 2:1

QFN20 4x4, 0.5P
CASE 485BH-01
ISSUE O

DATE 19 FEB 2010

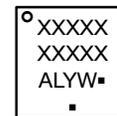


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	4.00 BSC	
D2	2.60	2.80
E	4.00 BSC	
E2	2.60	2.80
e	0.50 BSC	
K	0.20	---
L	0.35	0.45
L1	0.00	0.15

GENERIC MARKING DIAGRAM*

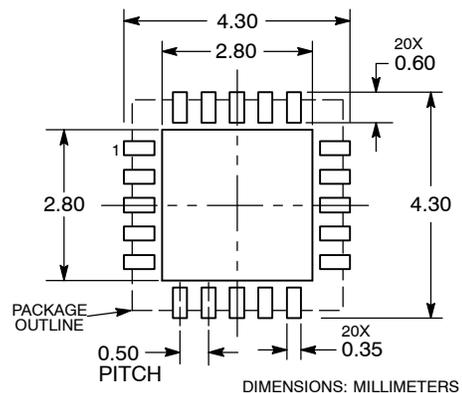


- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

MOUNTING FOOTPRINT



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NEW STANDARD:		
DESCRIPTION:	QFN20 4X4, 0.5P	PAGE 1 OF 2

